

PATENT NUMBER

<p>O.I.P.E.</p> <p>SCANNED <u>KSO</u> Q.A. <u>RC</u></p>	<p>PATENT DATE</p>
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APPLICANTS

TITLE

Microelectronic fabrication with upper lying aluminum fuse layer in copper interconnect semiconductor technology and method for fabrication thereof

PTO-2040
12/99

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	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
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